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**(54) THERMOPLASTIC RESIN COMPOSITION, PRODUCTION THEREOF, AND GAS-BARRIER FILM THEREFROM**

(57)Abstract:

**PURPOSE:** To obtain a thermoplastic resin composition in which a laminar silicate salt or a laminar phosphate salt is dispersed in a thermoplastic resin in a finely cleaved state, thus is useful as a film or the like because it is excellent in balance in mechanical properties, resistance to heat distortion and gas barrier properties.

**CONSTITUTION:** This composition comprises (A) a thermoplastic resin, for example, polypropylene resin or polyamide resin and (B) a laminar compound selected from a laminar silicate salt and a laminar phosphate compound having a substantially inactive compound (preferably an organic onium ion having 12 °C or more alkyl group) between layers wherein the amount of component B is 0.01-40wt.% calculated as ash and more than 40wt.% of component B is dispersed in component A in 0.05-10nm thickness. This composition is obtained in a powdery composite form by loading stress and compression force of higher than 500sec<sup>-1</sup> shear rate to a powdery mixture of components A and B simultaneously at a temperature lower than the softening point of component A.

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